Voltage Detector IC Series

# Free Delay Time Setting CMOS Voltage Detector IC Series

## BD52xx series BD53xx series

### ●General Description

Rohm's BD52xx and BD53xx series are highly accurate, low current consumption Voltage Detector ICs with a capacitor-controlled time delay. The line up includes BD52xx devices with N channel open drain output and BD53xx devices with CMOS output. The devices are available for specific detection voltages ranging from 2.3V to 6.0V in increments of 0.1V.

### ●Features

- Delay Time Controlled by external Capacitor
- Two output types (N channel open drain and CMOS output)
- Ultra-low current consumption
- Very small and low height package
- Package SSOP5 is similar to SOT-23-5(JEDEC)

### ●Key Specifications

- Detection voltage: 2.3V to 6.0V (Typ.) 0.1V steps
- High accuracy detection voltage: ±1.0%
- Ultra-low current consumption: 0.95µA (Typ.)

### ●Package

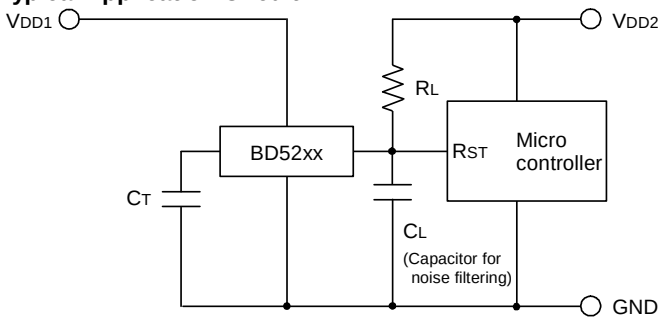
SSOP5: 2.90mm x 2.80mm x 1.25mm

VSOF5: 1.60mm x 1.60mm x 0.60mm

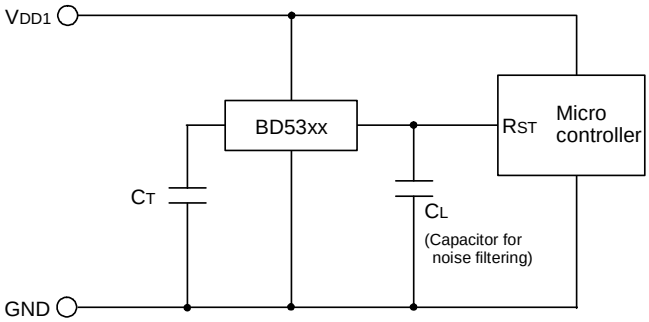
### ●Applications

Circuits using microcontrollers or logic circuits that require a reset.

### ●Typical Application Circuit




Open Drain Output type
BD52xx Series

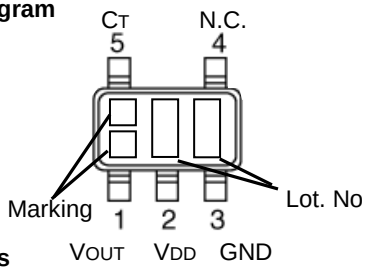



CMOS Output type
BD53xx Series

### ●Connection Diagram

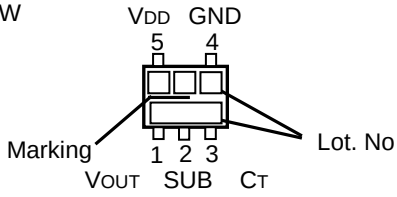
**SSOP5**

TOP VIEW




**VSOF5**

TOP VIEW




### ●Pin Descriptions

| SSOP5 | | |
|---|---|---|
| PIN No. | Symbol | Function |
| 1 | VOUT | Reset Output |
| 2 | VDD | Power Supply Voltage |
| 3 | GND | GND |
| 4 | N.C. | Unconnected Terminal |
| 5 | $C_T$ | Capacitor connection terminal for output delay time |

| VSOF5 | | |
|---|---|---|
| PIN No. | Symbol | Function |
| 1 | VOUT | Reset Output |
| 2 | SUB | Substrate* |
| 3 | $C_T$ | Capacitor connection terminal for output delay time |
| 4 | GND | GND |
| 5 | VDD | Power Supply Voltage |

*Connect the substrate to GND.

○Product structure：Silicon monolithic integrated circuit ○This product is not designed for protection against radioactive rays

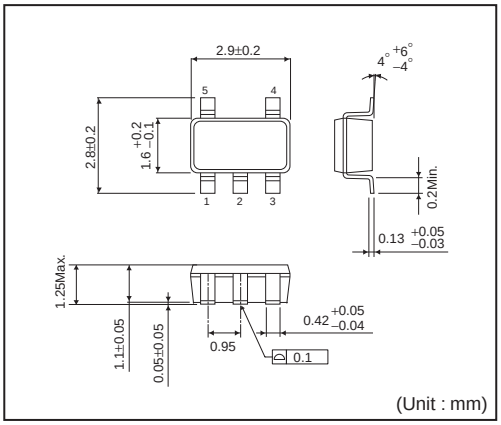

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●**Ordering Information**

| B | D | x | x | x | x | x | − | T | R |
|---|---|---|---|---|---|---|---|---|---|

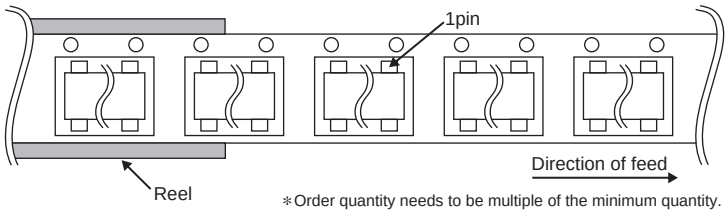
| Part Number | Output Type<br>52 : Open Drain<br>53 : CMOS | Reset Voltage Value<br>23 : 2.3V<br>⇩ 0.1V step<br>60 : 6.0V | Package<br>G : SSOP5<br>FVE : VSOF5 | Packaging and forming specification<br>TR : Embossed tape and reel |
|---|---|---|---|---|

**SSOP5**



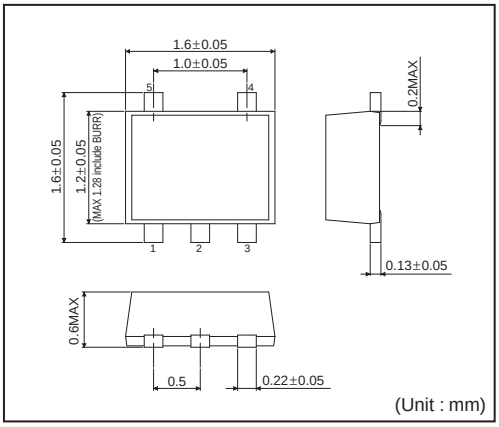

<Tape and Reel information>

| | |
|---|---|
| Tape | Embossed carrier tape |
| Quantity | 3000pcs |
| Direction of feed | TR<br>( The direction is the 1pin of product is at the upper right when you hold reel on the left hand and you pull out the tape on the right hand ) |




∗Order quantity needs to be multiple of the minimum quantity.

**VSOF5**





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●**Lineup**

| Output Type | Open Drain | | CMOS | |
|---|---|---|---|---|
| Detection Voltage | Marking | Part Number | Marking | Part Number |
| 6.0V | PW | BD5260 | RW | BD5360 |
| 5.9V | PV | BD5259 | RV | BD5359 |
| 5.8V | PU | BD5258 | RU | BD5358 |
| 5.7V | PT | BD5257 | RT | BD5357 |
| 5.6V | PS | BD5256 | RS | BD5356 |
| 5.5V | PR | BD5255 | RR | BD5355 |
| 5.4V | PQ | BD5254 | RQ | BD5354 |
| 5.3V | PP | BD5253 | RP | BD5353 |
| 5.2V | PN | BD5252 | RN | BD5352 |
| 5.1V | PM | BD5251 | RM | BD5351 |
| 5.0V | PL | BD5250 | RL | BD5350 |
| 4.9V | PK | BD5249 | RK | BD5349 |
| 4.8V | PJ | BD5248 | RJ | BD5348 |
| 4.7V | PH | BD5247 | RH | BD5347 |
| 4.6V | PG | BD5246 | RG | BD5346 |
| 4.5V | PF | BD5245 | RF | BD5345 |
| 4.4V | PE | BD5244 | RE | BD5344 |
| 4.3V | PD | BD5243 | RD | BD5343 |
| 4.2V | PC | BD5242 | RC | BD5342 |
| 4.1V | PB | BD5241 | RB | BD5341 |
| 4.0V | PA | BD5240 | RA | BD5340 |
| 3.9V | MV | BD5239 | QV | BD5339 |
| 3.8V | MU | BD5238 | QU | BD5338 |
| 3.7V | MT | BD5237 | QT | BD5337 |
| 3.6V | MS | BD5236 | QS | BD5336 |
| 3.5V | MR | BD5235 | QR | BD5335 |
| 3.4V | MQ | BD5234 | QQ | BD5334 |
| 3.3V | MP | BD5233 | QP | BD5333 |
| 3.2V | MN | BD5232 | QN | BD5332 |
| 3.1V | MM | BD5231 | QM | BD5331 |
| 3.0V | ML | BD5230 | QL | BD5330 |
| 2.9V | MK | BD5229 | QK | BD5329 |
| 2.8V | MJ | BD5228 | QJ | BD5328 |
| 2.7V | MH | BD5227 | QH | BD5327 |
| 2.6V | MG | BD5226 | QG | BD5326 |
| 2.5V | MF | BD5225 | QF | BD5325 |
| 2.4V | ME | BD5224 | QE | BD5324 |
| 2.3V | MD | BD5223 | QD | BD5323 |


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●**Absolute maximum ratings**

| Parameter | | Symbol | Limits | Unit |
|---|---|---|---|---|
| Power Supply Voltage | | $V_{DD}$-GND | -0.3 to +10 | V |
| Output Voltage | Nch Open Drain Output | $V_{OUT}$ | GND-0.3 to +10 | V |
| | CMOS Output | | GND-0.3 to $V_{DD}$+0.3 | |
| Output Current | | Io | 80 | mA |
| Power Dissipation | SSOP5 *1*3 | Pd | 540 | mW |
| | VSOF5 *2*3 | | 210 | |
| Operating Temperature | | Topr | -40 to +105 | °C |
| Ambient Storage Temperature | | Tstg | -55 to +125 | °C |

*1 Reduced by 5.4mW/°C when used over 25°C.
*2 Reduced by 2.1mW/°C when used over 25°C.
*3 When mounted on ROHM standard circuit board (70mm×70mm×1.6mm, glass epoxy board).

●**Electrical characteristics (Unless Otherwise Specified Ta=-40 to 105°C)**

| Parameter | Symbol | Condition | | Limit Min. | Limit Typ. | Limit Max. | Unit |
|---|---|---|---|---|---|---|---|
| Detection Voltage | $V_{DET}$ | $V_{DD}$=H→L, $R_L$=470kΩ *1 | | $V_{DET}$(T) ×0.99 | $V_{DET}$(T) | $V_{DET}$(T) ×1.01 | V |
| | | VDET=2.5V | Ta=+25°C | 2.475 | 2.5 | 2.525 | |
| | | | Ta=-40°C to 85°C | 2.418 | - | 2.584 | |
| | | | Ta=85°C to 105°C | 2.404 | - | 2.597 | |
| | | VDET=3.0V | Ta=+25°C | 2.970 | 3.0 | 3.030 | |
| | | | Ta=-40°C to 85°C | 2.901 | - | 3.100 | |
| | | | Ta=85°C to 105°C | 2.885 | - | 3.117 | |
| | | VDET=3.3V | Ta=+25°C | 3.267 | 3.3 | 3.333 | |
| | | | Ta=-40°C to 85°C | 3.191 | - | 3.410 | |
| | | | Ta=85°C to 105°C | 3.173 | - | 3.428 | |
| | | VDET=4.2V | Ta=+25°C | 4.158 | 4.2 | 4.242 | |
| | | | Ta=-40°C to 85°C | 4.061 | - | 4.341 | |
| | | | Ta=85°C to 105°C | 4.039 | - | 4.364 | |
| | | VDET=4.8V | Ta=+25°C | 4.752 | 4.8 | 4.848 | |
| | | | Ta=-40°C to 85°C | 4.641 | - | 4.961 | |
| | | | Ta=85°C to 105°C | 4.616 | - | 4.987 | |
| Circuit Current when ON | IDD1 | VDD=VDET-0.2V | $V_{DET}$ =2.3-3.1V | - | 0.80 | 2.40 | µA |
| | | | $V_{DET}$ =3.2-4.2V | - | 0.85 | 2.55 | |
| | | | $V_{DET}$ =4.3-5.2V | - | 0.90 | 2.70 | |
| | | | $V_{DET}$ =5.3-6.0V | - | 0.95 | 2.85 | |
| Circuit Current when OFF | IDD2 | VDD=VDET+2.0V | $V_{DET}$ =2.3-3.1V | - | 0.75 | 2.25 | µA |
| | | | $V_{DET}$ =3.2-4.2V | - | 0.80 | 2.40 | |
| | | | $V_{DET}$ =4.3-5.2V | - | 0.85 | 2.55 | |
| | | | $V_{DET}$ =5.3-6.0V | - | 0.90 | 2.70 | |
| Operating Voltage Range | VOPL | VOL≤0.4V, Ta=25 to 105°C, $R_L$=470kΩ | | 0.95 | - | - | V |
| | | VOL≤0.4V, Ta=-40 to 25°C, $R_L$=470kΩ | | 1.20 | - | - | |
| 'Low' Output Voltage (Nch) | VOL | VDD=1.5V, ISINK = 0.4 mA, VDET=2.3-6.0V | | - | - | 0.5 | V |
| | | VDD=2.4V, ISINK = 2.0 mA, VDET=2.7-6.0V | | - | - | 0.5 | |
| 'High' Output Voltage (Pch) | VOH | VDD=4.8V, ISOURCE=0.7 mA, VDET(2.3V to 4.2V) | | VDD-0.5 | - | - | V |
| | | VDD=6.0V, ISOURCE=0.9 mA, VDET(4.3V to 5.2V) | | VDD-0.5 | - | - | |
| | | VDD=8.0V, ISOURCE=1.1 mA, VDET(5.3V to 6.0V) | | VDD-0.5 | - | - | |

$V_{DET}$ (T) : Standard Detection Voltage (2.3V to 6.0V, 0.1V step)
$R_L$: Pull-up resistor to be connected between $V_{OUT}$ and power supply.
Design Guarantee. (Outgoing inspection is not done on all products.)
*1 Guaranteed at Ta=25°C.


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●**Electrical characteristics (Unless Otherwise Specified Ta=-40 to 105°C) - continued**

| Parameter | Symbol | Condition | Limit | | | Unit |
|---|---|---|---|---|---|---|
| | | | Min. | Typ. | Max. | |
| Leak Current | $I_{leak}$ | $V_{DD}=V_{DS}=10V$ *1 | - | - | 0.1 | µA |
| $C_T$ pin Threshold Voltage | $V_{CTH}$ | $V_{DD}=V_{DET}\times1.1$, $V_{DET}$=2.3-2.6V, $R_L$=470kΩ | $V_{DD}$ ×0.30 | $V_{DD}$ ×0.40 | $V_{DD}$ ×0.60 | V |
| | | $V_{DD}=V_{DET}\times1.1$, $V_{DET}$=2.7-4.2V, $R_L$=470kΩ | $V_{DD}$ ×0.30 | $V_{DD}$ ×0.45 | $V_{DD}$ ×0.60 | |
| | | $V_{DD}=V_{DET}\times1.1$, $V_{DET}$=4.3-5.2V, $R_L$=470kΩ | $V_{DD}$ ×0.35 | $V_{DD}$ ×0.50 | $V_{DD}$ ×0.60 | |
| | | $V_{DD}=V_{DET}\times1.1$, $V_{DET}$=5.3-6.0V, $R_L$=470kΩ | $V_{DD}$ ×0.40 | $V_{DD}$ ×0.50 | $V_{DD}$ ×0.60 | |
| Output Delay Resistance | $R_{CT}$ | $V_{DD}=V_{DET}\times1.1$ $V_{CT}$=0.5V *1 | 5.5 | 9 | 12.5 | MΩ |
| $C_T$ pin Output Current | $I_{CT}$ | $V_{CT}$=0.1V $V_{DD}$=0.95V *1 | 15 | 40 | - | µA |
| | | $V_{CT}$=0.5V $V_{DD}$=1.5V | 150 | 240 | - | |
| Detection Voltage Temperature coefficient | $V_{DET}/\Delta T$ | Ta=-40°C to 105°C | - | ±100 | ±360 | ppm/°C |
| Hysteresis Voltage | $\Delta V_{DET}$ | $V_{DD}$=L→H→L, $R_L$=470kΩ | $V_{DET}$ ×0.03 | $V_{DET}$ ×0.05 | $V_{DET}$ ×0.08 | V |

$V_{DET}$ (T) : Standard Detection Voltage (2.3V to 6.0V, 0.1V step)
$R_L$: Pull-up resistor to be connected between $V_{OUT}$ and power supply.
Design Guarantee. (Outgoing inspection is not done on all products.)
*1 Guaranteed at Ta=25°C.


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●**Block Diagrams**

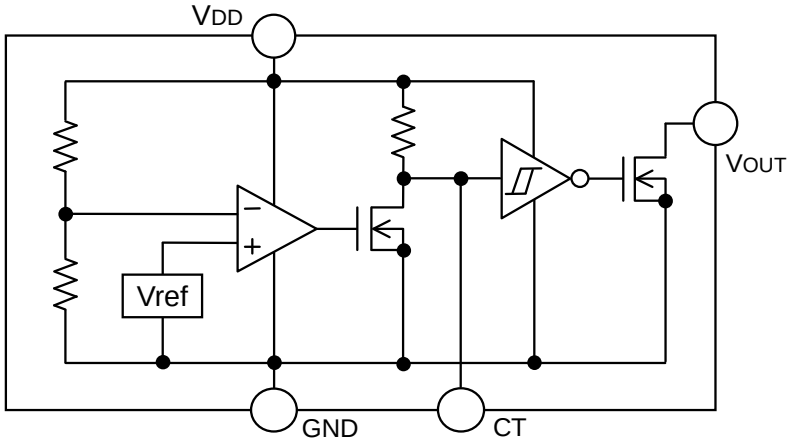



Fig.1 BD52xx Series

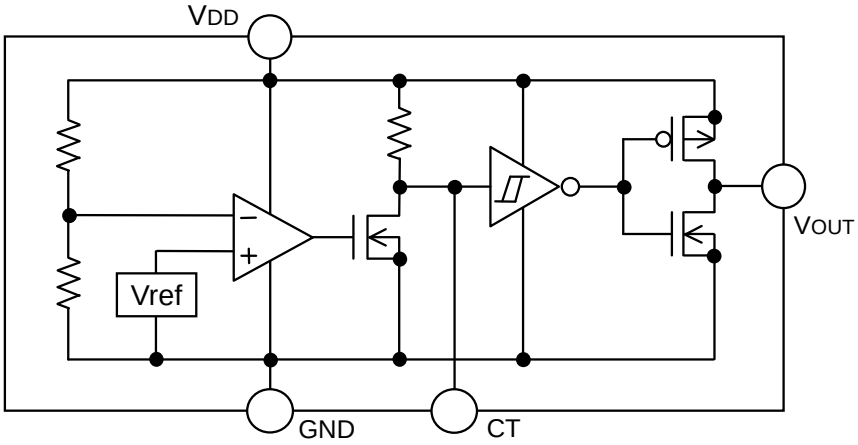



Fig.2 BD53xx Series


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●**Typical Performance Curves**

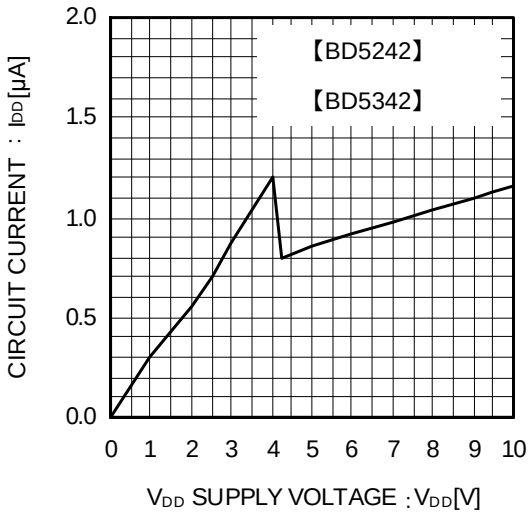



Fig.3 Circuit Current

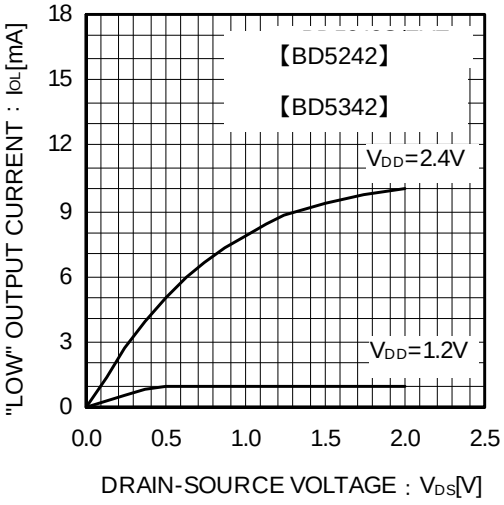



Fig.4 “Low” Output Current

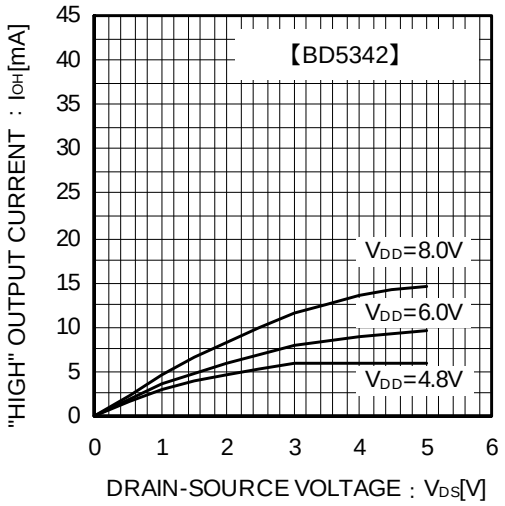



Fig.5 “High” Output Current

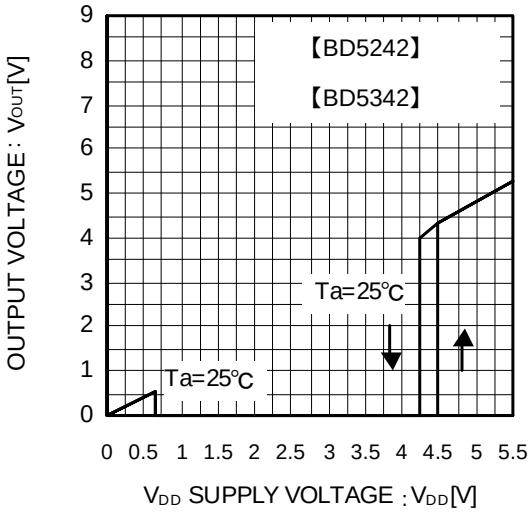



Fig.6 I/O Characteristics


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●**Typical Performance Curves – continued**

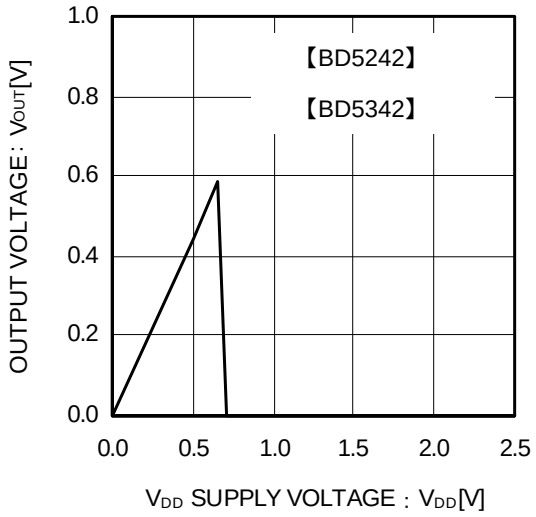



Fig.7 Operating Limit Voltage

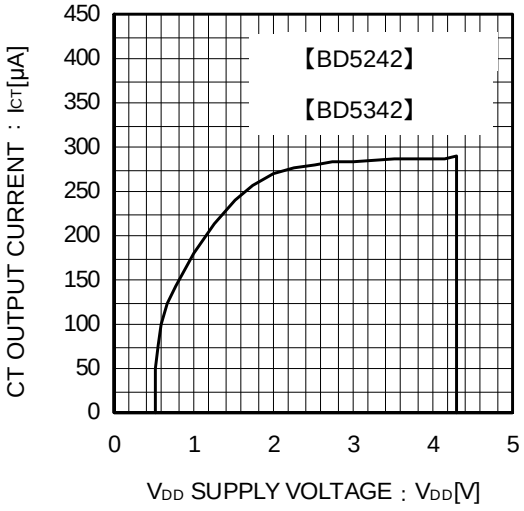



Fig.8 CT Terminal Current

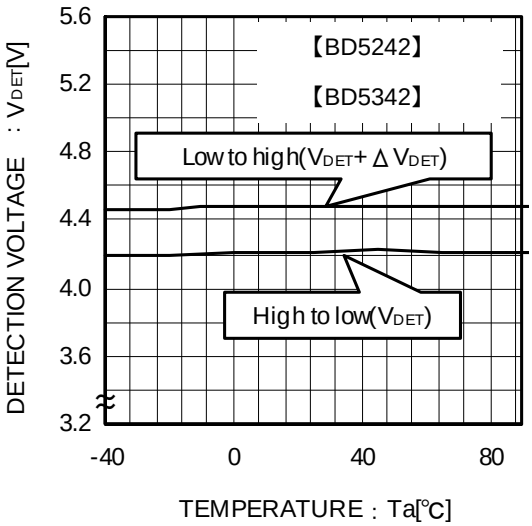



Fig.9 Detection Voltage
Release Voltage

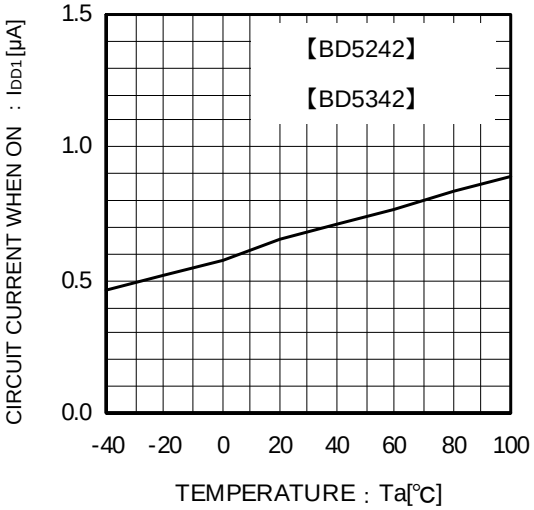



Fig.10 Circuit Current when ON


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●**Typical Performance Curves – continued**

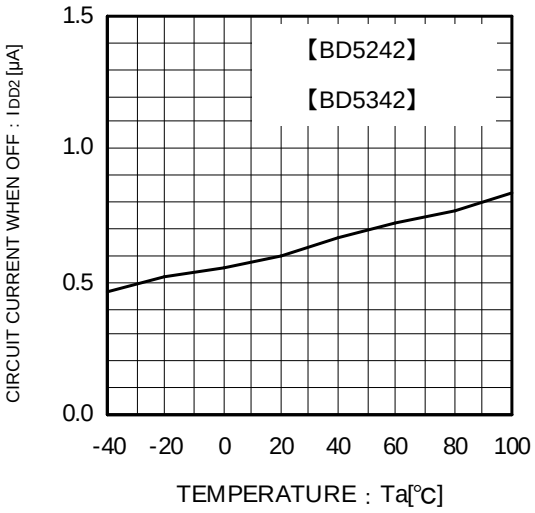



Fig.11 Circuit Current when OFF

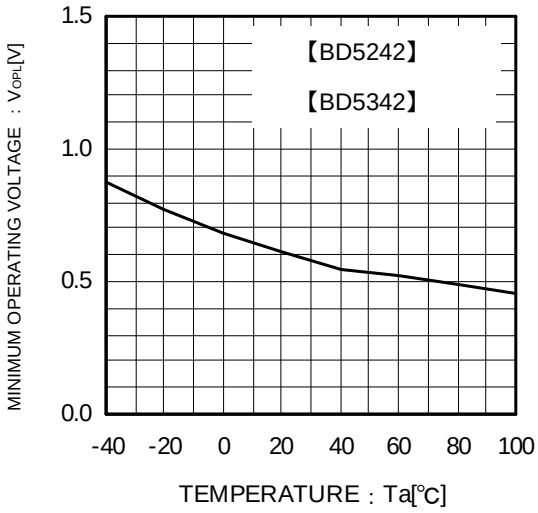



Fig.12 Operating Limit Voltage

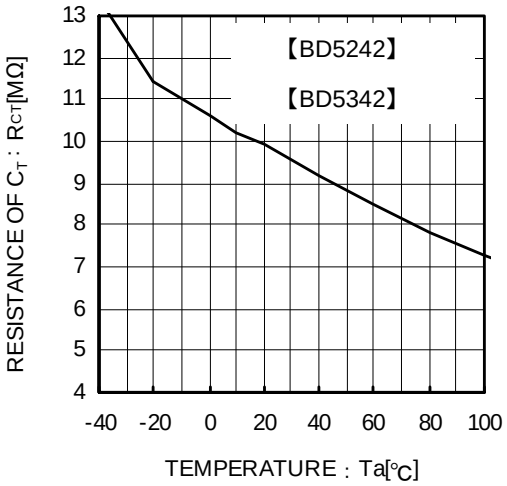



Fig.13 $C_T$ Terminal Circuit Resistance

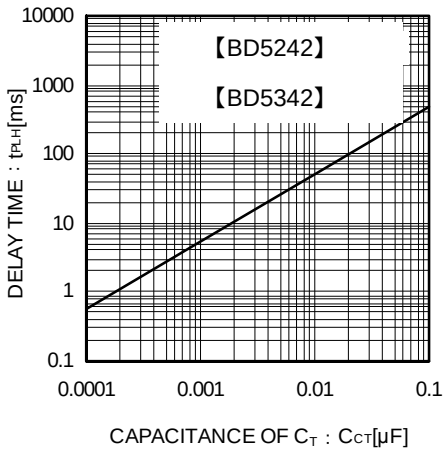



Fig.14 Delay Time ($t_{PLH}$) and
$C_T$ Terminal External Capacitance


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## ●Application Information

### Explanation of Operation

For both the open drain type (Fig.15) and the CMOS output type (Fig.16), the detection and release voltages are used as threshold voltages. When the voltage applied to the $V_{DD}$ pins reaches the applicable threshold voltage, the $V_{OUT}$ terminal voltage switches from either “High” to “Low” or from “Low” to “High”. Please refer to the Timing Waveform and Electrical Characteristics for information on hysteresis. Because the BD52xx series uses an open drain output type, it is necessary to connect a pull-up resistor to $V_{DD}$ or another power supply if needed [The output “High” voltage ($V_{OUT}$) in this case becomes $V_{DD}$ or the voltage of the other power supply].

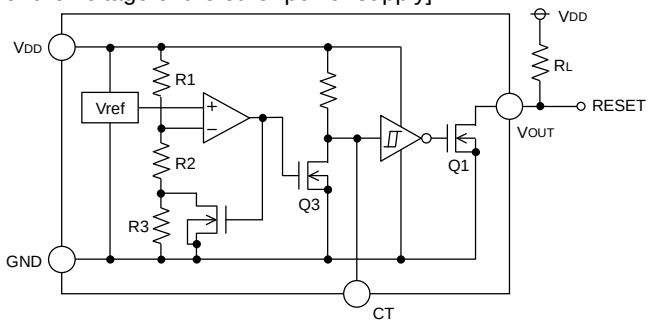



Fig.15 (BD52xxType Internal Block Diagram)

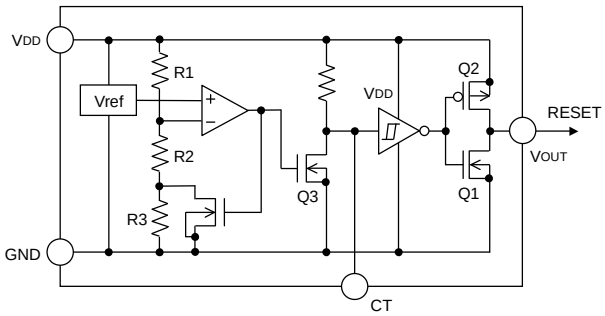



Fig.16 (BD53xxType Internal Block Diagram)

### Setting of Detector Delay Time

It is possible to set the delay time at the rise of VDD using a capacitor connected to the Ct terminal.

Delay time at the rise of $V_{DD}$ $t_{PLH}$: Time until when Vout rise to 1/2 of $V_{DD}$ after $V_{DD}$ rise up and beyond the release voltage($V_{DET}+\Delta V_{DET}$)

$$t_{PLH} = -C_{CT} \times R_{CT} \times \ln\left(\frac{V_{DD}-V_{CTH}}{V_{DD}}\right)$$

$C_{CT}$: $C_T$ pin External Capacitance

$R_{CT}$: $C_T$ pin Internal Impedance（Please refer to Electrical Characteristics.）

$V_{CTH}$: $C_T$ pin Threshold Voltage（Please refer to Electrical Characteristics.）

ln : Natural Logarithm

### Reference Data of Falling Time ($t_{PHL}$) Output

Examples of Falling Time ($t_{PHL}$) Output

| Part Number | $t_{PHL}$[µs] -40°C | $t_{PHL}$[µs] ,+25°C | $t_{PHL}$[µs],+105°C |
|---|---|---|---|
| BD5227 | 30.8 | 30 | 28.8 |
| BD5327 | 26.8 | 26 | 24.8 |

*This data is for reference only.

The figures will vary with the application, so please confirm actual operating conditions before use.

### Timing Waveforms

Example: the following shows the relationship between the input voltage VDD, the $C_T$ Terminal Voltage VCT and the output voltage VOUT when the input power supply voltage VDD is made to sweep up and sweep down (The circuits are those in Figure.15 and 16).

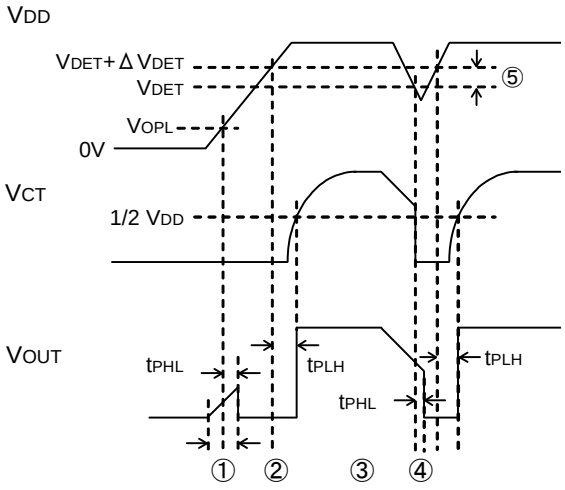



Fig.17 Timing Waveform

① When the power supply is turned on, the output is unstable from after over the operating limit voltage (VOPL) until tPHL. Therefore it is possible that the reset signal is not outputted when the rise time of $V_{DD}$ is faster than tPHL.

② When VDD is greater than VOPL but less than the reset release voltage (VDET+ΔVDET), the $C_T$ terminal (VCT) and output (VOUT) voltages will switch to L.

③ If VDD exceeds the reset release voltage (VDET+ΔVDET), then VOUT switches from L to H (with a delay due to the $C_T$ terminal).

④ If VDD drops below the detection voltage (VDET) when the power supply is powered down or when there is a power supply fluctuation, VOUT switches to L (with a delay of tPHL).

⑤ The potential difference between the detection voltage and the release voltage is known as the hysteresis width (ΔVDET). The system is designed such that the output does not toggle with power supply fluctuations within this hysteresis width, preventing malfunctions due to noise.


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●Circuit Applications

1) Examples of a common power supply detection reset circuit

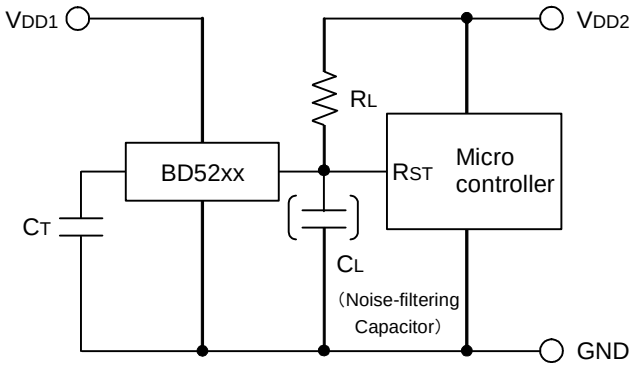



Fig.18 Open Drain Output Type

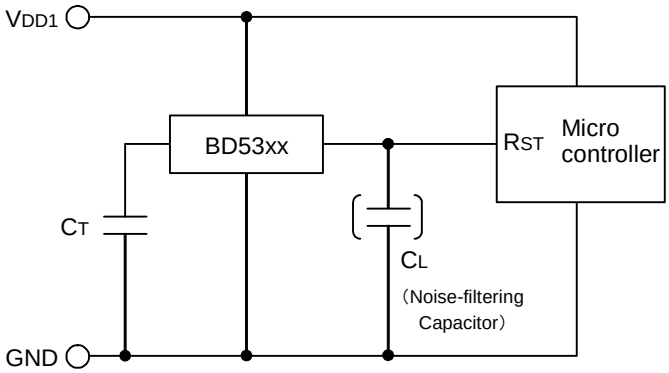



Fig.19 CMOS Output Type

Application examples of BD52xx series (Open Drain output type) and BD53xx series (CMOS output type) are shown below.

CASE1: Power supply of the microcontroller ($V_{DD2}$) differs from the power supply of the reset detection ($V_{DD1}$).
Use an open drain output type (BD52xx) device with a load resistance $R_L$ attached as shown Fig.18.

CASE2: Power supply of the microcontroller ($V_{DD1}$) is the same as the power supply of the reset detection ($V_{DD1}$).
Use a CMOS output type (BD53xx) device or an open drain output type (BD52xx) device with a pull up resistor between the output and $V_{DD1}$.

When a capacitance $C_L$ for noise filtering is connected to the $V_{OUT}$ pin (the reset signal input terminal of the microcontroller), please take into account the waveform of the rise and fall of the output voltage ($V_{OUT}$).

Please refer to Operational Notes for recommendations on resistor and capacitor values.

2) The following is an example of a circuit application in which an OR connection between two types of detection voltage resets the microcontroller.

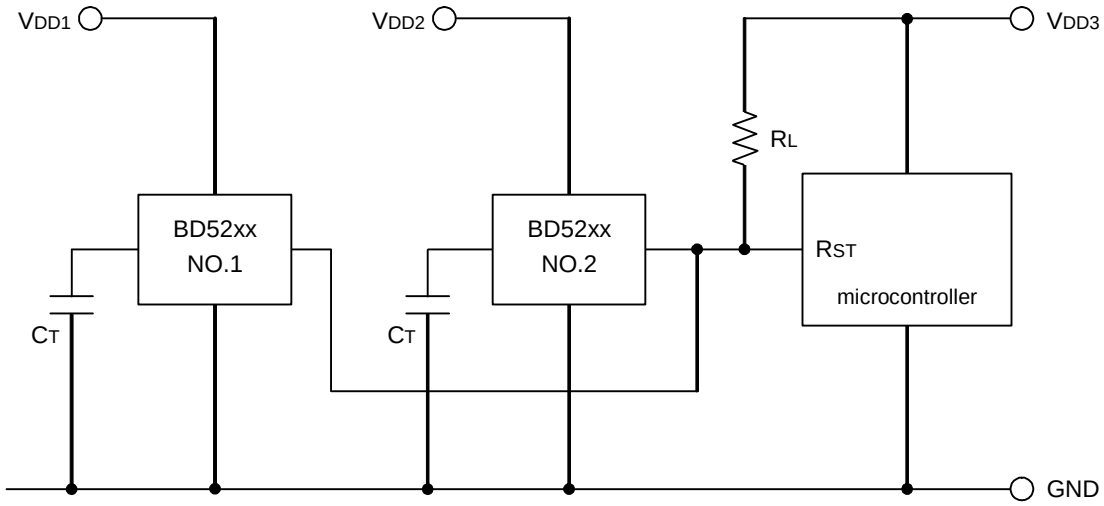



Fig.20

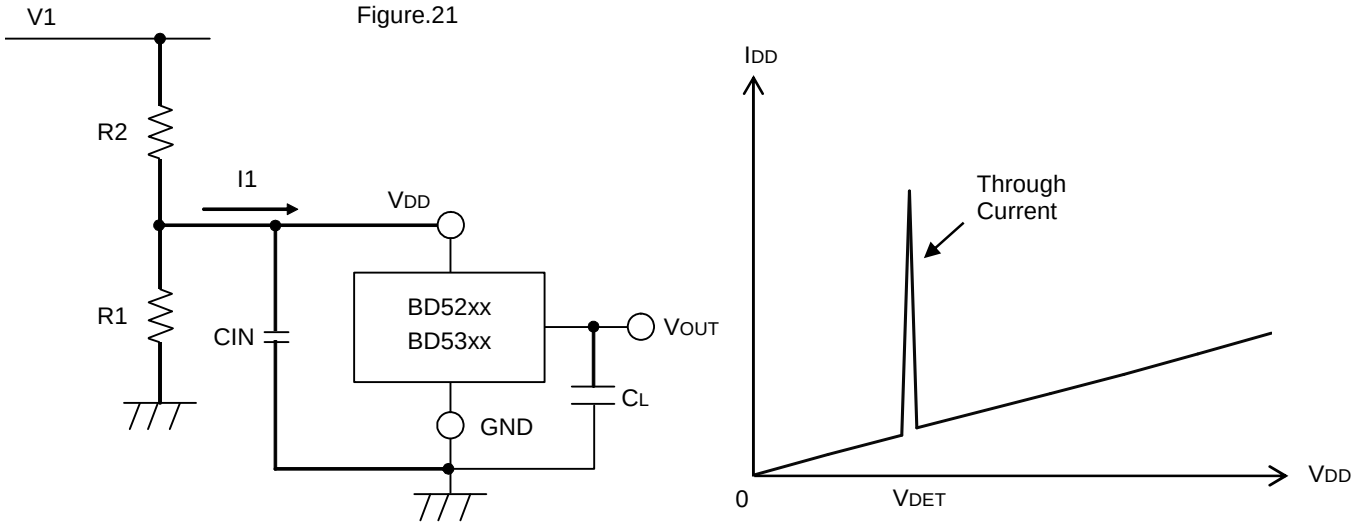
To reset the microcontroller when many independent power supplies are used in the system, OR connect an open drain output type (BD52xx series) to the microcontroller's input with pull-up resistor to the supply voltage of the microcontroller ($V_{DD3}$) as shown in Fig. 20. By pulling-up to $V_{DD3}$, output "High" voltage of micro-controller power supply is possible.


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3) Examples of the power supply with resistor dividers

In applications wherein the power supply voltage of an IC comes from a resistor divider circuit, an in-rush current will flow into the circuit when the output level switches from “High” to “Low” or vice versa. In-rush current is a sudden surge of current that flows from the power supply (VDD) to ground (GND) as the output logic changes its state. This current flow may cause malfunction in the systems operation such as output oscillations, etc.

Figure.21




When an in-rush current (I1) flows into the circuit (Refer to Fig. 21) at the time when output switches from “Low” to “High”, a voltage drop of I1×R2 (input resistor) will occur in the circuit causing the VDD supply voltage to decrease. When the VDD voltage drops below the detection voltage, the output will switch from “High” to “Low”. While the output voltage is at “Low” condition, in-rush current will stop flowing and the voltage drop will be reduced. As a result, the output voltage will switches again from “Low” to “High” which causes an in-rush current and a voltage drop. This operation repeats and will result to oscillation.

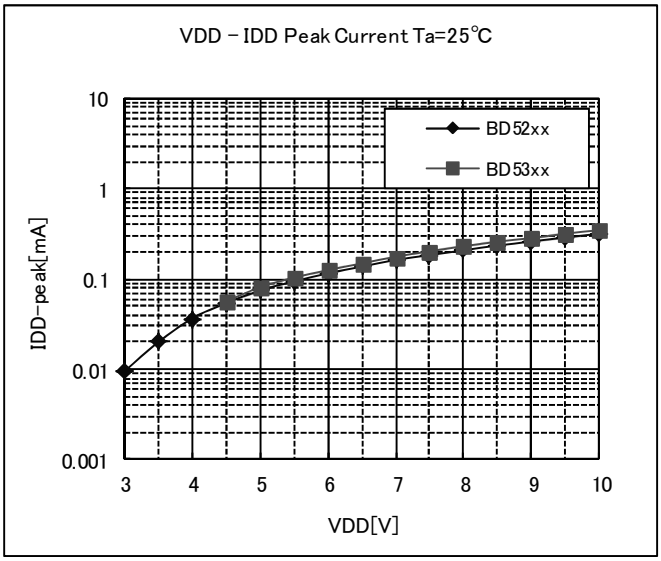



Figure.22 IDD Peak Current vs. Power Supply Voltage

* This data is for reference only.
The figures will vary with the application, so please confirm actual operating conditions before use.


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## ●Operational Notes

1) Absolute maximum ratings
Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

2) Ground Voltage
The voltage of the ground pin must be the lowest voltage of all pins of the IC at all operating conditions. Ensure that no pins are at a voltage below the ground pin at any time, even during transient condition.

3) Recommended operating conditions
These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

4) Bypass Capacitor for Noise Rejection
To help reject noise, put a 1µF capacitor between $V_{DD}$ pin and GND and 1000pF capacitor between $V_{OUT}$ pin and GND. Be careful when using extremely big capacitor as transient response will be affected.

5) Short between pins and mounting errors
Be careful when mounting the IC on printed circuit boards. The IC may be damaged if it is mounted in a wrong orientation or if pins are shorted together. Short circuit may be caused by conductive particles caught between the pins.

6) Operation under strong electromagnetic field
Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

7) The $V_{DD}$ line impedance might cause oscillation because of the detection current.

8) A $V_{DD}$ to GND capacitor (as close connection as possible) should be used in high $V_{DD}$ line impedance condition.

9) Lower than the mininum input voltage puts the $V_{OUT}$ in high impedance state, and it must be $V_{DD}$ in pull up ($V_{DD}$) condition.

10) External parameters
The recommended value of $R_L$ Resistor is 50kΩ to 1MΩ. The recommended value of $C_T$ Capacitor is over 100pF to 0.1µF. There are many factors (board layout, etc) that can affect characteristics. Please verify and confirm using practical applications.

11) Power on reset operation
Please note that the power on reset output varies with the $V_{DD}$ rise time. Please verify the behavior in the actual operation.

12) Testing on application boards
When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

13) Rush current
When power is first supplied to the IC, rush current may flow instantaneously. It is possible that the charge current to the parasitic capacitance of internal photo diode or the internal logic may be unstable. Therefore, give special consideration to power coupling capacitance, power wiring, width of GND wiring, and routing of connections.

14) $C_T$ pin discharge
Due to the capabilities of the $C_T$ pin discharge transistor, the $C_T$ pin may not completely discharge when a short input pulse is applied, and in this case the delay time may not be controlled. Please verify the actual operation.

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(Note1) Medical Equipment Classification of the Specific Applications

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| CLASSⅣ | | CLASSⅢ | |

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   [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
   [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including $Cl_2$, $H_2S$, $NH_3$, $SO_2$, and $NO_2$
   [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
   [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
   [f] Sealing or coating our Products with resin or other coating materials
   [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
   [h] Use of the Products in places subject to dew condensation

4. The Products are not subject to radiation-proof design.

5. Please verify and confirm characteristics of the final or mounted products in using the Products.

6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.

7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.

8. Confirm that operation temperature is within the specified range described in the product specification.

9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.

2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification


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### Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

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1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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   [b] the temperature or humidity exceeds those recommended by ROHM
   [c] the Products are exposed to direct sunshine or condensation
   [d] the Products are exposed to high Electrostatic

2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.

3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.

4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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